

**Amendments to the Claims**

The following listing of claims will replace all prior versions of claims in the application.

1. (Currently amended) A thermosetting adhesive sheet with electroconductive and thermoconductive properties, comprising:

a) a thermosetting adhesive sheet having two major surfaces, composed of a thermosetting adhesive composition having a melt coating temperature of between 60°C and 120°C, comprising an ethylene-glycidyl (meth)acrylate copolymer and a rosin, said rosin containing a carboxyl group, ~~where crosslinking is formed between the ethylene of said copolymer by electron beam radiation,~~ and having at least one through-opening region formed at a prescribed location,

b) low melting point solder placed within at least one through-opening region formed at the prescribed location, and

c) molten bonding between the solder and the adhesive composition, wherein the temperature where the solder undergoes melted flow and the melt coating temperature are substantially the same.

2-5. (Canceled)

6. (Previously Presented) A thermosetting adhesive sheet according to claim 1 wherein the melting point of the solder is below about 120°C.

7. (Currently Amended) A thermosetting adhesive sheet with electroconductive and thermoconductive properties, comprising:

(a) a thermosetting adhesive sheet, having a melt coating temperature, that is a solid at room temperature but can be thermo-compression bonded at temperatures of about 100 to about 200°C, and having a through-opening region formed at a prescribed location,

(b) low melting point solder placed within at least one-through-opening region formed at the prescribed location, and

(c) molten bonding between the solder and the adhesive composition, wherein the temperature where the solder undergoes melted flow and the melt coating temperature are substantially the same.

8. (Previously Presented) A thermosetting adhesive sheet according to claim 7 wherein the melting point of the solder is below about 120°C.

9. (Currently Amended) A method for using the thermosetting adhesive sheet according to claim 1 comprising:

~~Forming~~ forming a laminate structure having a first adherend and a second adherend and an adhesive layer between the two adherend layers, and

~~Subjecting~~ subjecting the laminate to a thermocompression bonding operation at a temperature of about 120 to about 300°C and a pressure of about 0.1 to about 100 kg/cm<sup>2</sup> ~~100 kg/cm<sup>2</sup>~~.

10. (Currently Amended) A method for using the thermosetting adhesive sheet according to claim 7 comprising:

~~Forming~~ forming a laminate structure having a first adherend and a second adherend and an adhesive layer between the two adherend layers, and

~~Subjecting~~ subjecting the laminate to a thermocompression bonding operation at a temperature of about 120 to about 300°C and a pressure of about 0.1 to about 100 kg/cm<sup>2</sup> ~~100 kg/cm<sup>2</sup>~~.